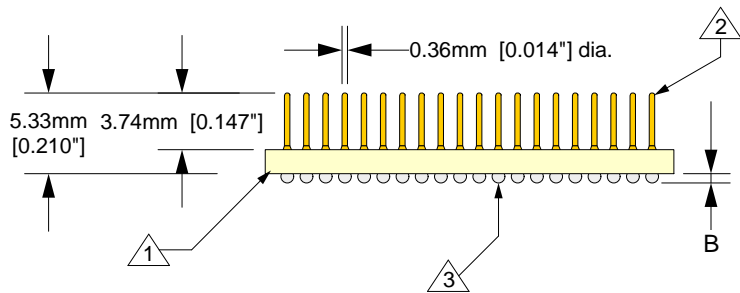


Top View
(reference only)

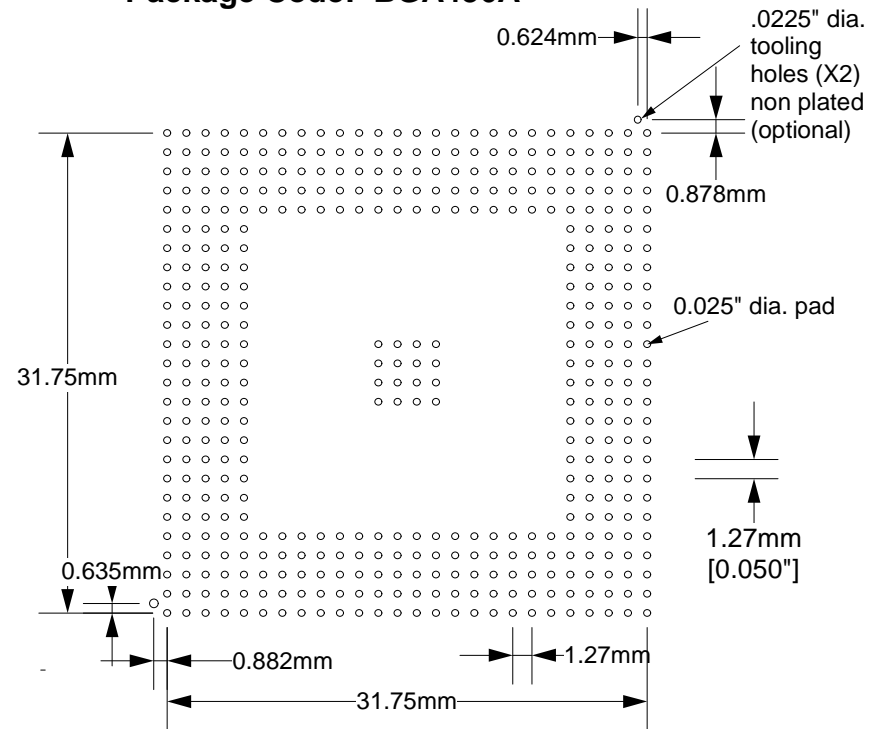


Side View
(reference only)

Note: SMT foot is independent of actual BGA package thickness.

- 1 Substrate: 1.59mm \pm 0.18mm [0.0625" \pm 0.007"] FR4/G10 or equivalent high temp material. Non-clad.
- 2 Pins: material- Brass Alloy 360 1/2 hard; finish- 0.25 μ m [10 μ "] Au over 1.27 μ m [50 μ "] Ni (min.).
- 3 Balls: Eutectic 63/37 SnPb. Thermally isolated from terminal pins

Package Code: BGA436A




Top View: Recommended Target PCB layout
Scale: 2:1

Pin Count	436
Array Size	26X26X5
Pitch	.050"
Body size (XxY)	35.0mm(1.378") X 35.0mm(1.378")
MGA Location (CxY)	1.63mm(0.064") X 1.63mm(0.064")
Ball Thickness (B)	0.024"

Description: BGA Emulator Foot (SM base).

436 position terminal pins (MGA, Mini-grid Array) to solder balls. Surface mounts to target BGA land pattern.

 <p>SF-BGA436A-B-11 Drawing</p> <p>© 2004 IRONWOOD ELECTRONICS, INC. PO BOX 21151 ST. PAUL, MN 55121 Tele: (651) 452-8100 www.ironwoodelectronics.com</p>	Status: Released	Scale -	Rev: A
	Drawing: B. Roux		Date: 10/21/04
	File: SF-BGA436A-B-11 Dwg.mcd		Modified:

Tolerances: diameters \pm 0.03mm [\pm 0.001"], PCB perimeters \pm 0.13mm [\pm 0.005"], PCB thicknesses \pm 0.18mm [\pm 0.007"], pitches (from true position) \pm 0.08mm [\pm 0.003"], all other tolerances \pm 0.13mm [\pm 0.005"] unless stated otherwise. Materials and specifications are subject to change without notice.